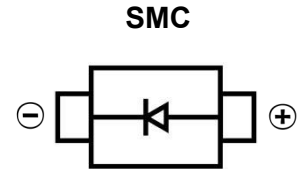


SCHOTTKY BARRIER DIODE
FEATURES

- Small foot print, surface mountable
- Very low forward voltage drop
- High frequency operation
- Guard ring for enhanced ruggedness and long term reliability
- Lead (Pb)-free ("PbF" suffix)
- Designed and qualified for industrial level


MECHANICAL DATA

- Case: SMC(DO-214AB)
- Case Material: Molded Plastic. UL flammability
- Classification Rating: 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Weight: 0.21 grams (approximate)



MAJOR RATINGS AND CHARACTERISTICS			
SYMBOL	CHARACTERISTICS	VALUES	UNITS
$I_{F(AV)}$	Rectangular waveform	3.0	A
V_{RRM} / V_R		40	V
I_{FSM}	$t_p = 5 \mu s$ sine	2000	A
V_F	3.0 Apk, $T_J = 125^\circ C$	0.43	V
T_J	Range	- 55 to 150	$^\circ C$

VOLTAGE RATINGS			
PARAMETER	SYMBOL	30BQ040	UNITS
Maximum DC reverse voltage	V_R	40	V
Maximum working peak reverse voltage	V_{RWM}		

ABSOLUTE MAXIMUM RATINGS					
PARAMETER	SYMBOL	TEST CONDITIONS		VALUES	UNITS
Maximum average forward current	$I_{F(AV)}$	50 % duty cycle at $T_L = 118^\circ C$, rectangular waveform		3.0	A
		50 % duty cycle at $T_L = 110^\circ C$, rectangular waveform		4.0	
Maximum peak one cycle non-repetitive surge current	I_{FSM}	5 μs sine or 3 μs rect. pulse	Following any rated load condition and with rated V_{RRM} applied	2000	
		10 ms sine or 6 ms rect. pulse		110	
Non-repetitive avalanche energy	E_{AS}	$T_J = 25^\circ C$, $I_{AS} = 1.0 A$, $L = 12 mH$		6.0	mJ
Repetitive avalanche current	I_{AR}	Current decaying linearly to zero in 1 μs Frequency limited by T_J maximum $V_A = 1.5 \times V_R$ typical		1.0	A

ELECTRICAL SPECIFICATIONS					
PARAMETER	SYMBOL	TEST CONDITIONS		VALUES	UNITS
Maximum forward voltage drop	$V_{FM}^{(1)}$	3 A	$T_J = 25^\circ C$	0.53	V
		6 A		0.68	
		3 A	$T_J = 125^\circ C$	0.43	
		6 A		0.57	
Maximum reverse leakage current	$I_{RM}^{(1)}$	$T_J = 25^\circ C$	$V_R = \text{Rated } V_R$	0.5	mA
		$T_J = 125^\circ C$		30	
Maximum junction capacitance	C_T	$V_R = 5 V_{DC}$ (test signal range 100 kHz to 1 MHz) $25^\circ C$		230	pF
Typical series inductance	L_S	Measured lead to lead 5 mm from package body		3.0	nH
Maximum voltage rate of change	dV/dt	Rated V_R		10 000	V/ μs

Note

(1) Pulse width < 300 μs , duty cycle < 2 %

SCHOTTKY BARRIER DIODE

THERMAL - MECHANICAL SPECIFICATIONS				
PARAMETER	SYMBOL	TEST CONDITIONS	VALUES	UNITS
Maximum junction and storage temperature range	$T_J^{(1)}, T_{Stg}$		- 55 to 150	°C
Maximum thermal resistance, junction to lead	$R_{thJL}^{(2)}$	DC operation	12	°C/W
Maximum thermal resistance, junction to ambient	R_{thJA}		46	
Approximate weight			0.24	g
			0.008	oz.
Marking device		Case style SMC (similar to DO-214AB)	V3F	

Notes

(1) $\frac{dP_{tot}}{dT_J} < \frac{1}{R_{thJA}}$ thermal runaway condition for a diode on its own heatsink

(2) Mounted 1" square PCB

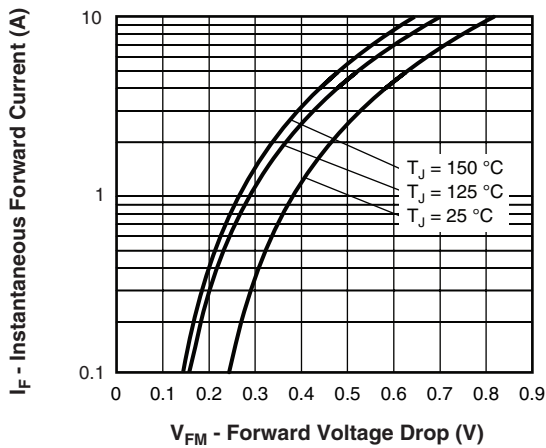
Typical Characteristics


Fig. 1 - Maximum Forward Voltage Drop Characteristics (Per Leg)

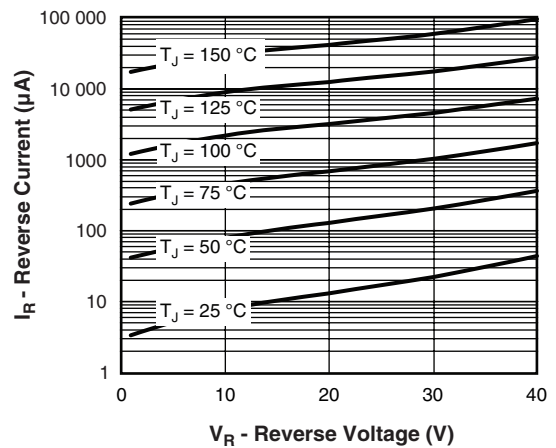


Fig. 2 - Typical Values of Reverse Current vs. Reverse Voltage (Per Leg)

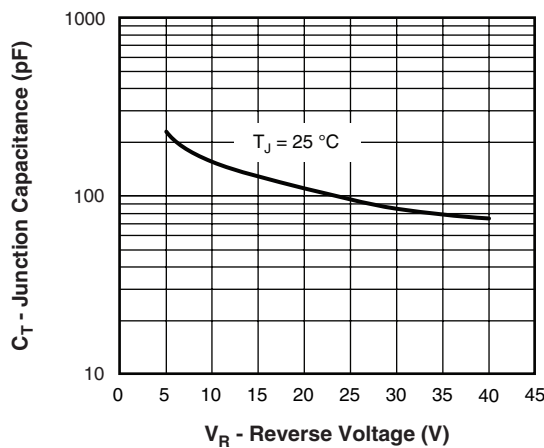


Fig. 3 - Typical Junction Capacitance vs. Reverse Voltage (Per Leg)

SCHOTTKY BARRIER DIODE

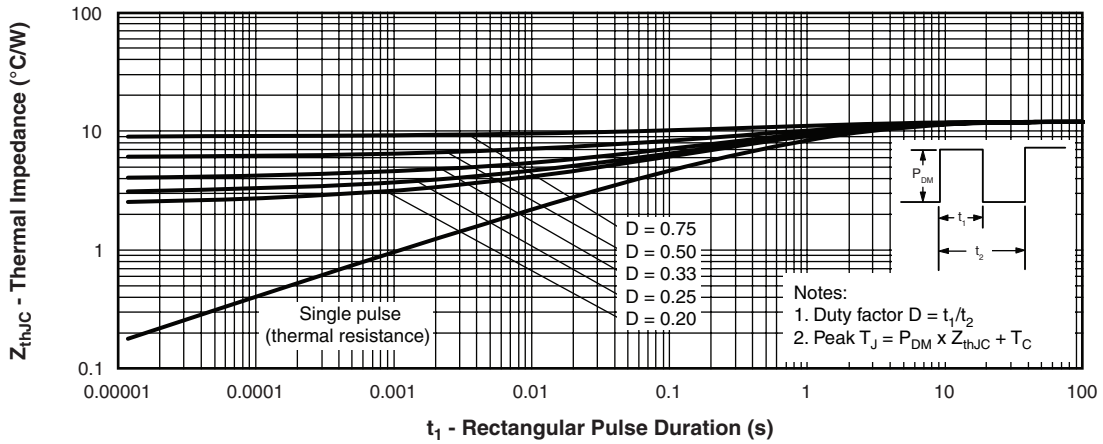


Fig. 4 - Maximum Thermal Impedance Z_{thJC} Characteristics (Per Leg)

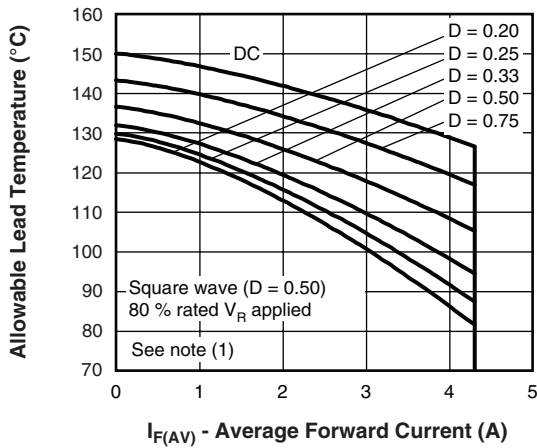


Fig. 5 - Maximum Average Forward Current vs. Allowable Lead Temperature

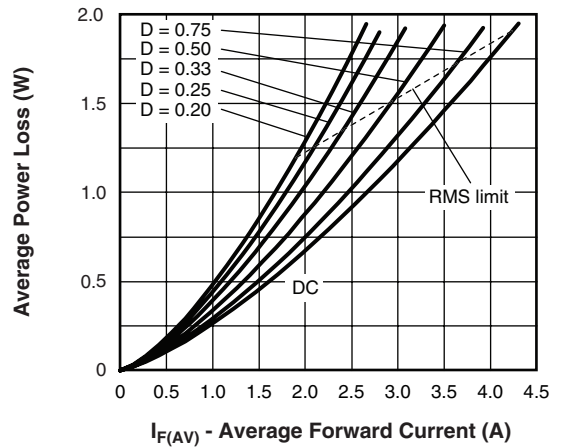


Fig. 6 - Maximum Average Forward Dissipation vs. Average Forward Current

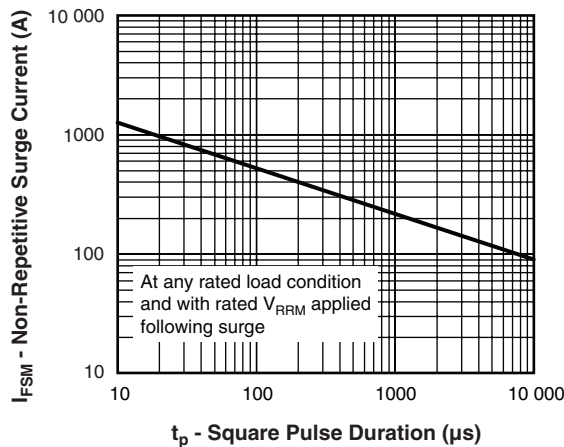
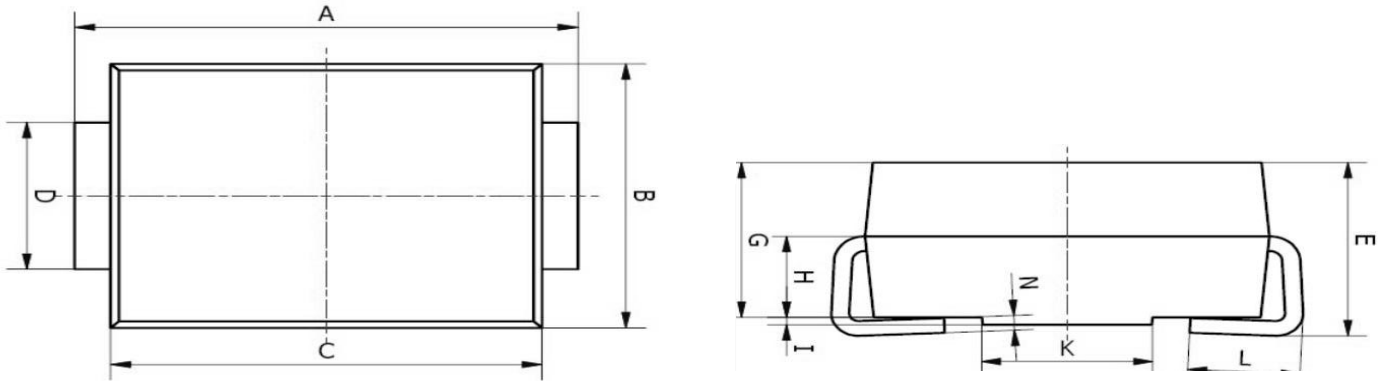


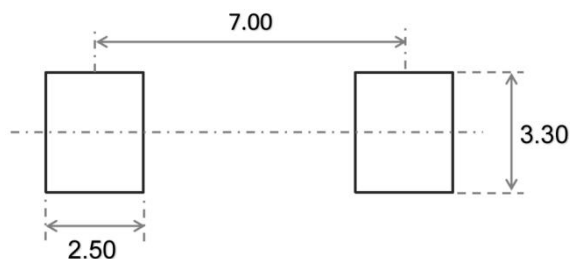
Fig. 7 - Maximum Peak Surge Forward Current vs. Pulse Duration

Note

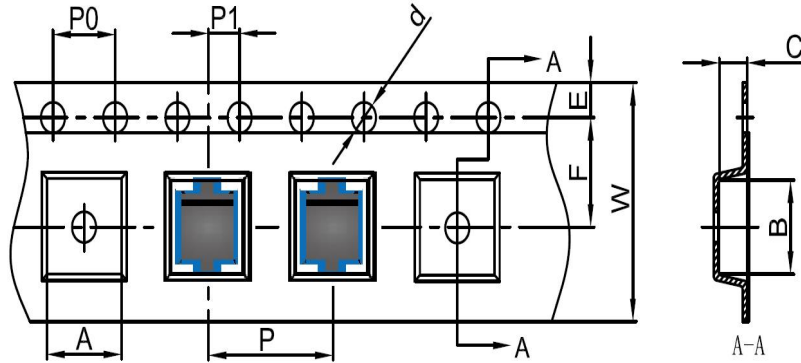
- (1) Formula used: $T_C = T_J - (P_d + P_{d_{REV}}) \times R_{thJC}$;
 P_d = Forward power loss = $I_{F(AV)} \times V_{FM}$ at $(I_{F(AV)}/D)$ (see fig. 6);
 $P_{d_{REV}}$ = Inverse power loss = $V_{R1} \times I_R (1 - D)$; I_R at $V_{R1} = 80\%$ rated V_R

SCHOTTKY BARRIER DIODE
SMC Package Outline Dimensions


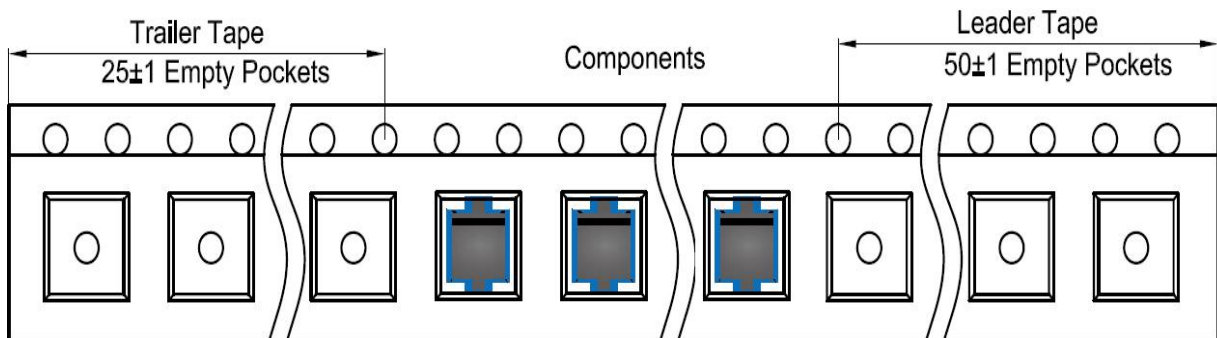
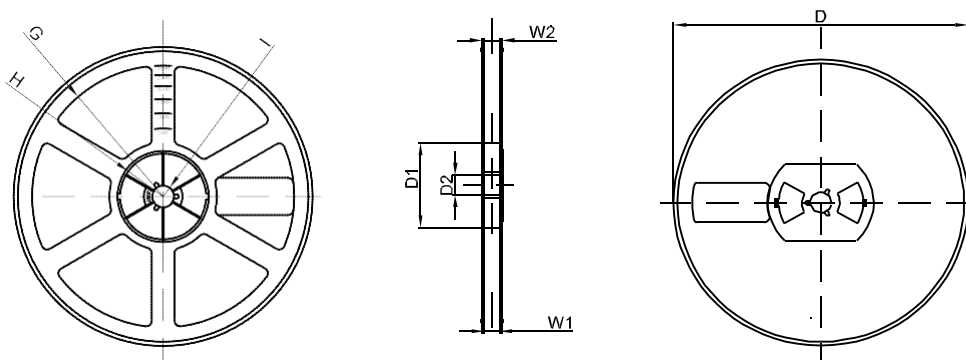
Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min.	Max.	Min.	Max.
A	7.75	8.13	0.305	0.320
B	5.59	6.22	0.220	0.245
C	6.60	7.11	0.260	0.280
D	2.75	3.25	0.108	0.128
E	2.25	2.82	0.089	0.111
G	2.00	2.62	0.079	0.103
H	1.26	1.56	0.050	0.061
I	0.05	0.15	0.002	0.006
K	4.30	6.00	0.169	0.236
L	1.25	1.75	0.049	0.069
N	0.10	0.30	0.004	0.012

SMC Suggested Pad Layout

Note:

1. Controlling dimension: in millimeters
2. General tolerance: $\pm 0.05\text{mm}$
3. The pad layout is for reference purposes only

SCHOTTKY BARRIER DIODE
SMC Tape and Reel
SMC Embossed Carrier Tape


DIMENSIONS ARE IN MILLIMETER										
TYPE	A	B	C	d	E	F	P0	P	P1	W
SMC	6.3	8.25	2.90	Ø1.55	1.75	7.50	4.00	8.00	2.00	16.00
TOLERANCE	±0.1	±0.1	±0.1	±0.1	±0.1	±0.1	±0.1	±0.1	±0.1	±0.1

SMC Tape Leader and Trailer

SMC Reel


DIMENSIONS ARE IN MILLIMETER								
REEL OPTION	D	D1	D2	G	H	I	W1	W2
13" DIA	Ø330	100	21	R165	R50	R6.50	16.4	21.00
TOLERANCE	±2	±1	±1	±1	±1	±1	±1	±1